## PMP11012_REVA BOM

C100, C101, R100 added by hand

<table>
<thead>
<tr>
<th>COUNT</th>
<th>RefDes</th>
<th>Value</th>
<th>Description</th>
<th>Size</th>
<th>Part Number</th>
<th>Mfr</th>
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<tbody>
<tr>
<td>1</td>
<td>PCB</td>
<td></td>
<td>PMP5040 rev A PCB</td>
<td></td>
<td>PMP5040 rev A PCB</td>
<td>any</td>
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<td>1</td>
<td>C1</td>
<td>100pF</td>
<td>Capacitor, Ceramic, 2kV, C0G, 10%</td>
<td>1812</td>
<td>Std</td>
<td>Std</td>
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<tr>
<td>1</td>
<td>C100</td>
<td>0.01uF</td>
<td>Capacitor, Ceramic, 50V, X7R, 10%</td>
<td>0603</td>
<td>C1608X7R1H03K</td>
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<tr>
<td>1</td>
<td>C11</td>
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<td>Capacitor, Ceramic, 16V, X7R, 20%</td>
<td>0603</td>
<td>C1608X7R1C105M</td>
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<tr>
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<td>TDK</td>
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<tr>
<td>1</td>
<td>C14</td>
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<td>1</td>
<td>C15</td>
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<td>Std</td>
<td>Std</td>
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<tr>
<td>1</td>
<td>C2</td>
<td>82uF</td>
<td>Capacitor, Aluminum Electrolytic, 63V</td>
<td>0.315 inch</td>
<td>83V ZL 82uF 10 X 12.5</td>
<td>Rubycon</td>
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<td>1</td>
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<td>2.2uF</td>
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<td>C3225X7R2A225M</td>
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<td>3</td>
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<td>22uF</td>
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<td>Capacitor, Aluminum, 10-V, FK Series</td>
<td>0.268 x 0.307</td>
<td>EEVFK1A151P</td>
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<td>2</td>
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<tr>
<td>1</td>
<td>D1</td>
<td>9.1V</td>
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<td>BZX84C9V1LT1</td>
<td>ON Semiconductor</td>
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<tr>
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<td>D2</td>
<td>9V</td>
<td>Diode, Rectifier, 1A, 200V</td>
<td>SOT23</td>
<td>MURA120</td>
<td>ON Semi</td>
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<td>15V</td>
<td>Diode, Zener, 15-V</td>
<td>SOT23</td>
<td>BZX84C15LT1</td>
<td>ON Semiconductor</td>
</tr>
<tr>
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<td>D5</td>
<td>BAV99</td>
<td>Diode, Dual Ultra Fast, Series, 200-mA, 70-V</td>
<td>SOT23</td>
<td>BAV99</td>
<td>Fairchild</td>
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<tr>
<td>2</td>
<td>J1, J2</td>
<td></td>
<td>Terminal Block, 2-pin, 6-A, 3.5mm</td>
<td>0.27 x 0.25&quot;</td>
<td>ED1514</td>
<td>OST</td>
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<tr>
<td>1</td>
<td>L1</td>
<td>1uH</td>
<td>Inductor, SMT, 10A, 6miliOhm</td>
<td>0.402 x 0.394 inch</td>
<td>MSS1038-102NL</td>
<td>Coilcraft</td>
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<tr>
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<td>Q1</td>
<td>FDS2572</td>
<td>MOSFET, N-Chan, 150V, 4.9A, 47miliOhm</td>
<td>SO8</td>
<td>FDS2572</td>
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<td>Q2</td>
<td>MMBT2222A</td>
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<td>MMBT2222ALT1</td>
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<td>1</td>
<td>R1</td>
<td>7.5k</td>
<td>Resistor, Chip, 1-W, 5%</td>
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<td>Std</td>
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<td>1</td>
<td>R11</td>
<td>40.2k</td>
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<td>R14, R18</td>
<td>6.19k</td>
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<td>R2</td>
<td>402k</td>
<td>Resistor, Chip, 1/16W, 1%</td>
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<tr>
<td>2</td>
<td>R3, R9, R15, R17</td>
<td>10k</td>
<td>Resistor, Chip, 1/16W, 1%</td>
<td>0603</td>
<td>Std</td>
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<td>2</td>
<td>R4, R100</td>
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<td>Resistor, Chip, 1/16W, 1%</td>
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<td>R5, R10</td>
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<td>Std</td>
<td>Std</td>
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<tr>
<td>4</td>
<td>R6, R12, R13, R16</td>
<td>1k</td>
<td>Resistor, Chip, 1/16W, 1%</td>
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<td>Std</td>
<td>Std</td>
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<tr>
<td>1</td>
<td>R7</td>
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<td>Std</td>
<td>Std</td>
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<td>1</td>
<td>R8</td>
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<td>Resistor, Chip, 1/16W, 5%</td>
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<td>Std</td>
<td>Std</td>
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<tr>
<td>1</td>
<td>T1</td>
<td>POE13F-50L</td>
<td>Transformer, SMT For PoE/PD, 13W</td>
<td>0.677 x 0.865 inch</td>
<td>POE13F-50L</td>
<td>Coilcraft</td>
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<td>2</td>
<td>TP1, TP3</td>
<td>5000</td>
<td>Test Point, Red, Thru Hole Color Keyed</td>
<td>0.100 x 0.100 inch</td>
<td>5000</td>
<td>Keystone</td>
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<tr>
<td>2</td>
<td>TP2, TP4</td>
<td>5000</td>
<td>Test Point, Black, Thru Hole Color Keyed</td>
<td>0.100 x 0.100 inch</td>
<td>5001</td>
<td>Keystone</td>
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<td>1</td>
<td>TP5</td>
<td>5000</td>
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<td>5000</td>
<td>Keystone</td>
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<tr>
<td>1</td>
<td>U1</td>
<td>TPS40210DGQ</td>
<td>IC, 4.5V-52V I/P, Current Mode Boost Controller</td>
<td>DGG10</td>
<td>TPS40210DGQ</td>
<td>TI</td>
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<tr>
<td>1</td>
<td>U2</td>
<td>TCMT1107</td>
<td>IC, Photocoupler, CTR = 80% - 160%</td>
<td>MF4</td>
<td>TCMT1107</td>
<td>Vishay</td>
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<tr>
<td>1</td>
<td>U3</td>
<td>TL431AIDBZ</td>
<td>IC, Precision Adjustable Shunt Regulator</td>
<td>SOT23-3</td>
<td>TL431AIDBZ</td>
<td>TI</td>
</tr>
</tbody>
</table>
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